

SOT234-1

plastic shrink dual in-line package; 24 leads (400 mil)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SDIP24
Package type industry code	SDIP24
Package style descriptive code	SDIP (shrink dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

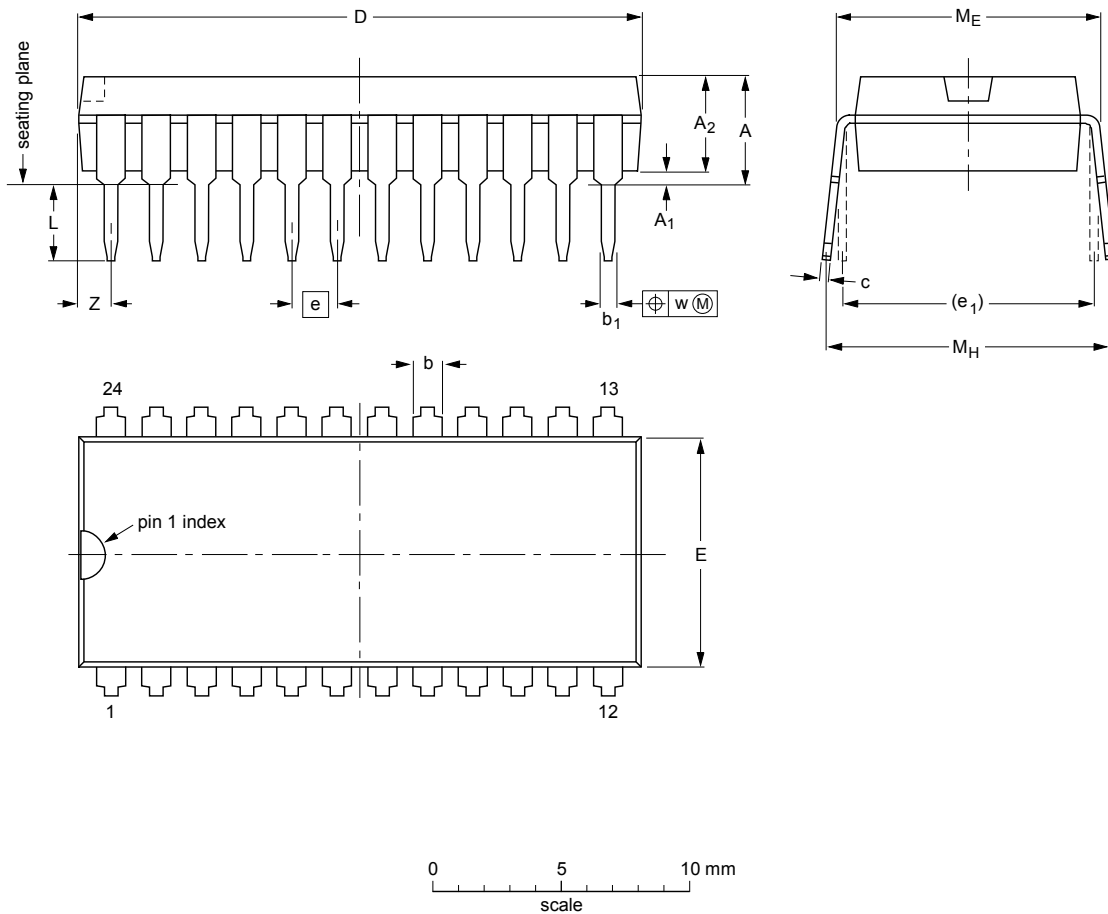
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.85	22.3	mm
E	package width	8.7	-	8.9	9.1	mm
A	seated height	[tbd]	-	4.7	4.7	mm
A ₂	package height	[tbd]	-	3.65	3.8	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

SDIP24: plastic shrink dual in-line package; 24 leads (400 mil)

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.8	1.3 0.8	0.53 0.40	0.32 0.23	22.3 21.4	9.1 8.7	1.778	10.16	3.2 2.8	10.7 10.2	12.2 10.5	0.18	1.6

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT234-1						95-02-04 03-02-13

Fig. 1. Package outline SDIP24 (SOT234-1)

3. Legal information

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